



**PATENT**

**THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Kinsman et al.

**Serial No.:** 09/917,127

**Filed:** July 27, 2001

**For:** METHOD FOR FABRICATING A  
CHIP SCALE PACKAGE USING WAFER  
LEVEL PROCESSING AND DEVICES  
RESULTING THEREFROM

**Confirmation No.:** 3326

**Examiner:** M. Trinh

**Group Art Unit:** 2822

**Attorney Docket No.:** 2269-3572.1US  
(97-1243.01/US)

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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**AMENDMENT UNDER 37 C.F.R. §1.116**

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Sir:

The following amendments and remarks are filed in response to the Examiner's remarks in the Final Office Action mailed October 16, 2003, the three-month shortened statutory period for response to which expires on January 16, 2004. This response is submitted on or before two months from the mailing date of the Final Office Action.

**Amendments to the Specification** begin on page 3 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 5 of this paper.

**Amendments to the Drawings** begin on page 9 of this paper and include both attached replacement sheets and annotated sheets showing changes.

**Remarks** begin on page 10 of this paper.